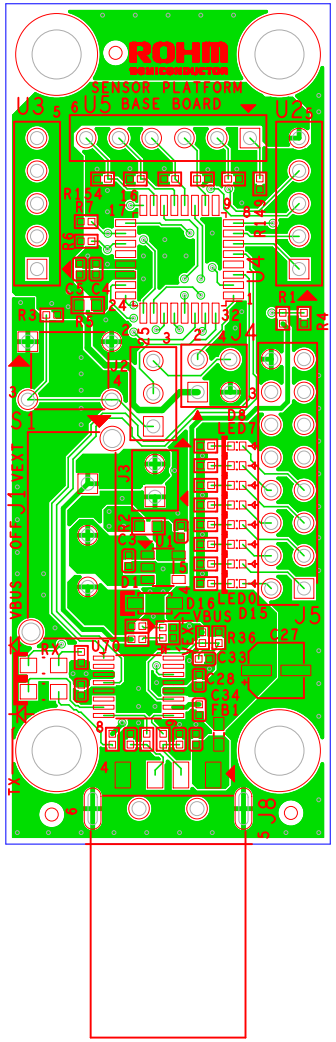


ROHM SEMICONDUCTOR	LAYER: 01 PRIMARY-SIDE	COMPANY NAME: ROHM SEMICONDUCTOR USA	UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES
	DESIGNER: PTHVDC	PROJECT NAME: SENSOR_PLATFORM_BASE_BOARD	TOLERANCES DECIMAL X ±.1 XX ±.03 XXX ±.010 ANGLE ±30 MACH FINISH √
	CHECKER: ROHM SEMICONDUCTOR		
	DATE: 2014-09-18	PROJECT NUMBER: NUMBER	REV. 02
	JOB#:		

	LAYER:02 SECONDARY-SIDE	COMPANY NAME: ROHM SEMICONDUCTOR USA	UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES DECIMAL ANGLE X ± .1 ± 30 XX ± .03 MACH FINISH XXX ± .010 √
ROHM SEMICONDUCTOR	DESIGNER: PTHYDC CHECKER: ROHM SEMICONDUCTOR	PROJECT NAME: SENSOR_PLATFORM_BASE_BOARD	
	DATE: 2014-09-18	PROJECT NUMBER: NUMBER	REV. 02
	JOB#:		

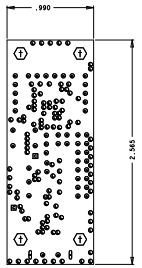
LAYER STACKING DETAIL

Layer #	Layer Type	Copper Weight (Oz)	Copper Thickness (Mils)	Material Type - Ply	Dielectric Thickness (Mils)
Plating			1.35		
1	SIG	0.5	0.65		
				Prepreg	58.00
2	SIG	0.5	0.65		
Plating			1.35		

Total Overal Thickness: 62.00+/-10%Mils
Material Ordering Info (used in lieu of Fasttrak data)

Panel Size	------
Number Up	------
Number of Parts Due	------
Prepregs Construction Added?	------
Material Ply Specified	------
Material Type (ie Nelco-29, 370 HR, ...)	FR4

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
⊙	12.0	+3.0/-10.0	PLATED	111
⊙	40.0	+3.0/-3.0	PLATED	48
⊙	43.0	+3.0/-3.0	PLATED	2
⊡	55.0	+3.0/-3.0	PLATED	2
ⓣ	150.0	+3.0/-3.0	PLATED	4
▯	98.0x28.0	+3.0/-3.0	PLATED	2



FAB NOTE

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED

NOTES:

1. Specifications.
   A. Fabricate IAW IPC600, latest revision.
   B. Producibility study - It is the respondsibility of the supplier to conduct a thorough review of the artwork and media for manufacturability in the supplier's process compliance to all applicable specifications. Customer must be advised in writing (in advance of manufacturing) of any changes, revisions,or corrections made or recommendations to ensure conformance to standards, and of any specifications that cannot be met.
   D. This drawing is to be used in conjunction with the provided gerber and drill data when applicable.
   E. All notes are "Unless Otherwise Specified."
2. Material
   A. FR4.
   B. Color to be opaque.
3. Soldermask
   Solder mask both sides with (green color) liquid photoimageable soldermask, 003 max. thickness.
   Soldermask over bare copper.
   Soldermask is allowed in via holes.
4. Drilling
   A. All hole diameters are finished sizes.
   B. All hole to be +/- .003 from true position unless otherwise specified.
   C. All hole diameters to be +/- .003 unless otherwise specified.
   D. An NC drill file has been supplied - see drill table.
5. Finish
   A. Plate thru with copper .0010 min to .002 max. thickness drill size dimension apply after plating.
   B. Use gold immersion over nickel.
   C. Finished boards shall not have nicks, scratches, voids, exposed copper, poor plating, all misdrilled holes.
6. Silkscreen
   A. Silkscreen using white non-conductive epoxy or equivalent (both sides).
   B. No silkscreen allowed on exposed lands.
   C. Silkscreen must be a minimum of 3mm away form fiducial marks.
   D. Minimum clearance between silkscreen legend and vias, pads, or holes to be .005.
   E. Silkscreen is allowed in via holes.
7. Electrical Test
   A. All boards shall be 100% electrically tested for opens/short at 10 volts. MIL-SPEC boards to be tested at 40 volts.
   B. Apply test stamp in non-legend area on solder side of PCB.
   C. Test is required on both sides of the board.
8. Cleanliness
   A. Boards shall be free of fiber glass dust or any other foreign material.
   B. Finished boards must conform to 0.01 MG/IN max NAcL ionic contamination as meaxured by the omega meter 600SMD.
9. Packaging
   There shall be a max of 25 units per package, individually wrapped, and shipped in cardboard cratons with sufficient surrounding material to prevend shipping damage.
10. Bow and Twist
    Bow and twist to be .007 IN/IN or .090 max according to IPC-A-600D.
11. Inspection
    A.Automatic optical inspection of all layers required.
    B.The impedance should be controlled by stackup layer.
12. Inside corners should be rounded-off
13. Changes to board geometries and apertures are not allowed unless they are approved by customer.
14. Rounding is allowed on 90 degree corners with the size of standard routing bit.

ROHM SEMICONDUCTOR

FAB DRAWING

DESIGNER: PTHYDC
CHECKER: INITIAL
DATE: 2014-09-18
JOB#:

COMPANY NAME: ROHM SEMICONDUCTOR USA
PROJECT NAME: SENSOR PLATFORM BASE BOARD
FAB NUMBER: NUMBER
REV: 02
SHEET: 1 OF 2

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES
TOLERANCES
DECIMAL: ANGLE
X.X=.10 X.XX=.030
X.XX=.010 MACH FINISH